

-- 30. An encapsulated die not having a substrate comprising:
a die having first and second surfaces, the first surface carrying bond pads; and
an encapsulation material sealing the second surface of the die.

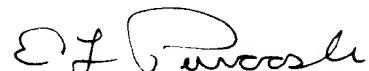
31. The encapsulated die of claim 30 wherein the encapsulation material seals the first surface of the die except for the bond pads.

32. The encapsulated die of claim 31 wherein the encapsulation material is chosen from a class consisting of epoxies, including thermo-set resins, silicons, sycar, polyimides and polyurethanes. --

Remarks

The instant preliminary amendment is filed to prosecute the non-elected claims from the parent application and to present new claims 30-32 drawn to an encapsulated semiconductor device for examination. No new matter has been added. A complete, clean set of the currently pending claims is attached.

Respectfully submitted,



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Entitled: OVERMOLDING ENCAPSULATION PROCESS AND ENCAPSULATED
ARTICLE MADE THEREFROM

COMPLETE, CLEAN SET OF PENDING CLAIMS

26. An overmolded die the size of a chip scale package and not having any substrate.
27. A chip scale packaged die having no substrate.
28. An overmolded die without a substrate, comprising:
a die having a first surface carrying electrical contacts; and
an encapsulated material sealing the die except for the electrical contacts.
29. The overmolded die of claim 28 wherein the encapsulated material is chosen from a class consisting of epoxies, including thermo-set resins, silicons, sycar, polyimides and polyurethanes.
30. An encapsulated die not having a substrate comprising:
a die having first and second surfaces, the first surface carrying bond pads; and
an encapsulation material sealing the second surface of the die.
31. The encapsulated die of claim 30 wherein the encapsulation material seals the first surface of the die except for the bond pads.
32. The encapsulated die of claim 31 wherein the encapsulation material is chosen from a class consisting of epoxies, including thermo-set resins, silicons, sycar, polyimides and polyurethanes.